



re: Shim et al.
Serial No.: 09/903,070
Filed: July 11, 2001
Page 2 of 9

RECEIVED
SEP 25 2003
TECHNOLOGY CENTER R3700

In the Claims:

1. (Currently Amended) A method for packing wafers comprising the steps of:
inserting wafers into a cassette;
~~putting a cassette in which wafers are inserted;~~ the cassette into a packing bag; and
sealing the packing bag by applying force to an outer surface of the packing bag,
opposite the cassette, so as to press the packing bag against an external form of the cassette
thereby allowing the packing bag to be tightly adhered along the external form of the cassette,
molding a border of the packing bag and cutting an unnecessary border of the packing bag.
2. (Currently Amended) The method for packing wafers according to Claim 1,
wherein the wafers are 300 mm caliber wafers. ~~putting the cassette in which wafers are~~
~~inserted, into the packing bag comprises:~~
~~putting the cassette in which 300 mm caliber wafers are inserted, into the packing bag.~~
3. (Original) The method for packing wafers according to Claim 1, wherein the
step of putting a cassette into a packing bag comprises the steps of:
sealing the cassette in a polypropylene bag; and
putting the cassette sealed by the polypropylene bag, into an aluminum bag.
4. (Original) The method for packing wafers according to Claim 3, wherein the
step of sealing the cassette in a polypropylene bag comprises the steps of:
putting the cassette into the polypropylene bag; and
sealing the polypropylene bag by maintaining the polypropylene bag in a state of
being loose with respect to the external form of the cassette.
5. (Previously Presented) The method for packing wafers according to Claim 3,
wherein a border of the aluminum bag is molded in the step of sealing the packing bag.

6. (Original) The method for packing wafers according to Claim 1, wherein a vacuum is not necessary when the packing bag is tightly adhered along the external form of the cassette, in the step of sealing the packing bag.

7. (Currently Amended) A method for packing wafers comprising the steps of:
inserting wafers into a cassette;
sealing a the cassette ~~in which wafers are inserted~~, in a polypropylene bag;
putting the cassette in a state of being sealed by the polypropylene bag, into an aluminum bag; and
sealing the aluminum bag by applying force to an outer surface of the aluminum bag, opposite the polypropylene bag, so as to press the packing bag against an external form of the cassette thereby allowing the aluminum bag to be tightly adhered along the external form of the cassette, molding a border of the aluminum bag and cutting an unnecessary border of the aluminum bag.

8. (Currently Amended) The method for packing wafers according to Claim 7, wherein the wafers are 300 mm wafers. ~~sealing the cassette in which wafers are inserted, in the polypropylene bag, comprises:~~

~~sealing the cassette in which 300 mm wafers are inserted, in the polypropylene bag.~~

9. (Original) The method for packing wafers according to Claim 7, wherein the step of sealing a cassette in a polypropylene bag comprises the steps of:

putting the cassette into the polypropylene bag; and
sealing the polypropylene bag by maintaining the polypropylene bag in a state of being loose with respect to the external form of the cassette.

10. (Original) The method for packing wafers according to Claim 7, wherein a vacuum is not necessary when the aluminum bag is tightly adhered along the external form of the cassette, in the step of sealing the aluminum bag.

11. (Previously Presented) A method of packing a semiconductor wafer, comprising:

- inserting the semiconductor wafer in a carrying device;
- ~~providing a carrying device that holds the semiconductor wafer;~~
- inserting the carrying device into a packing bag; and
- molding the packing bag by applying force to an outer surface of the packing bag, opposite the carrying device, so as to press the packing bag against at least a portion of an external form of the carrying device such that a portion of the packing bag substantially conforms to the at least a portion of the external form of the carrying device.

12. (Original) A method as recited in Claim 11 wherein the packing bag is a second packing bag, the method further comprising:

- inserting the carrying device into a first packing bag; and
- wherein inserting the carrying device into the second packing bag comprises:
 - inserting the carrying device and the first packing bag into the second packing bag.

13. (Original) A method as recited in Claim 12, further comprising:

- sealing the first packing bag such that the carrying device remains in communication with the environment external to the first packing bag.

14. (Original) A method as recited in Claim 13, wherein sealing the first packing bag comprises:

- folding a portion of the first packing bag through which the carrying device was inserted.

15. (Previously Presented) A method as recited in Claim 12, wherein inserting the carrying device into a first packing bag comprises:

- inserting the carrying device into a polypropylene packing bag.

16. (Previously Presented) A method as recited in Claim 12, wherein inserting the carrying device into the second packing bag comprises:

inserting the carrying device into a aluminum packing bag.

17. (Original) A method as recited in Claim 12, wherein inserting the carrying device into the first packing bag, inserting the carrying device and the first packing bag into the second packing bag, and molding the second packing bag are performed in a packing room that is on a same level as a wafer cleaning room.

18. (Original) A method as recited in Claim 17, further comprising:
cleaning the semiconductor wafer before inserting the carrying device into the first packing bag, inserting the carrying device and the first packing bag into the second packing bag, and molding the second packing bag.

19. (Original) A method as recited in Claim 11, further comprising:
trimming a portion of the packing bag that does not substantially conform to the at least a portion of the external form of the carrying device.

20. (Currently Amended) A method as ~~recite~~ recited in Claim 11, wherein the semiconductor wafer is a 300 mm semiconductor wafer. providing the carrying device that holds the semiconductor wafer comprises:

~~providing the carrying device that holds a 300 mm caliber semiconductor wafer.~~
